



# SEMINAR 專題演講



國立中央大學 太空科學與工程學系

Department of Space Science and Engineering, National Central University

## Time

Friday, May 10 2024  
13:00 – 14:00

# Semiconductor technology trend and my career in tsmc

## Place

健雄館 (科四館)

S4-917 教室  
Room S4-917,  
Chien-Shiung Building

黃瑜真博士  
台積電晶片研發部門經理

Semiconductor is everywhere in our daily life, from smartphones, high performance computing, automotive, internet of things, to AI. Chips in electronic devices are all designed and manufactured by semiconductor industry. Semiconductors have driven advances in human life, communications, computing, health care, transportation, and countless other applications.

Computing workloads have evolved more over the past decade than perhaps the previous four decades. Cloud computing, big data analytics, artificial intelligence (AI), neural network training, AI inferencing, mobile computing on advanced smartphones and even self-driving cars are all pushing the computing envelope. Modern workloads have brought packaging technologies to the forefront for innovation and they are critical to a product's performance, function and cost. These modern workloads have pushed the product design to embrace a more holistic approach for optimization at the system level. tsmc 3DFabric offers the freedom and advantage to design the products more holistically as a system of chiplets that offers key advantages versus designing a larger monolithic die.